

REMARKS

Claims 21-24 and 27-37 remain pending in this application. By this amendment the abstract has been amended for clarification. Reconsideration and allowance in view of the amendments and the following remarks are respectfully requested.

Claims 21-24 and 27-35 are rejected under 35 U.S.C. §102(b) as being anticipated by Watanabe *et al.* (US 5,319,159, hereinafter "Watanabe"). Applicants respectfully assert that Watanabe fails to teach or suggest each and every feature of the claimed invention as required under §102(b). For example, Watanabe fails to teach or suggest, *inter alia*, "**pressing a conductive element** into the opening," as disclosed in method claim 21. To the contrary, Watanabe throughout only discloses disposing of conductive layers 2, 6, 7, 12, and 13 over the surface of a base plate 1. Further, element 9 in Watanabe is clearly an *epoxy resin* (i.e., NON-conductive element). Nowhere is the epoxy resin 9 in Watanabe ever taught, or suggested, to be a conductive element, as the Examiner alleged in the Final Office Action.

Second, Watanabe fails to teach or suggest, *inter alia*, "a conductive element **embedded into a laminate**," as disclosed in claim 27. To the contrary, Watanabe throughout only discloses disposing of conductive layers 2, 6, 7, 12, and 13 *over the surface* of the laminate.

CONCLUSION

Applicants respectfully submit that claims 21-24 and 27-37, are in condition for allowance and should forthwith issue as a Patent. If any fees, other than extension of time fees, are due as a result of this response, please charge the Deposit Account identified in the Application Transmittal Form. If the Examiner believes that anything further would be helpful to place the application in condition for allowance, the Examiner is invited to contact Applicant's representative at the telephone number listed below.

Date: January 7, 2003

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'A. Olsen', with a stylized flourish at the end.

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VERSION WITH MARKINGS TO SHOW CHANGES

The abstract has been amended as follows:

[The present invention provides an] An interconnect formed between layers of a circuit board[. A conductive object is embedded in the layer of a circuit board], wherein a conductive element is embedded in an opening within a laminate of the circuit board, and wherein the conductive element forms at least one contact pad extending beyond a surface of the laminate.